

SILICON ZENER DIE

Features:

- Zener Voltage 2.4V - 47V
- Withstand Large Surge Stresses

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Nominal Power Dissipation	P_D	Derate above 25 °C	500	mW
Forward Voltage	V_F	@ $I_F=10\text{mA}$, Pulse, $T_J = 25\text{ °C}$	0.9	V
Operating Temperature Range	T_J	-	-55 to +150	°C
Storage Temperature Range	T_{stg}	-	-55 to +150	°C

**TECHNICAL DATA
DATA SHEET D0123 REV. -**

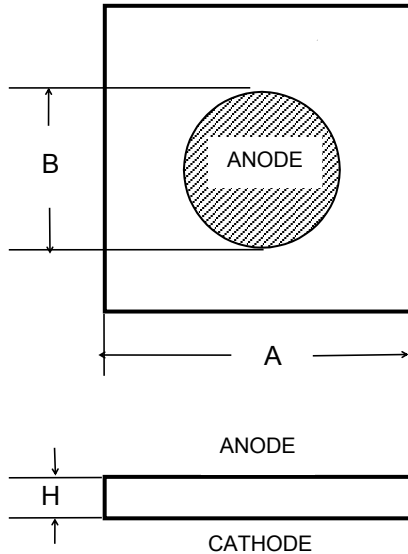
Electrical Characteristics @ T_J=25 °C:

Device	Zener voltage		Zener Impedence			Leakage Current	
	Nom. VZ ①	@ I _{ZT}	Max.	Max.	@ I _{ZK}	Max. I _R @ V _R	
			Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}			
	Volts	mA	Ω	Ω	mA	uA	Volts
SZ212V4	2.4	20	30	1200	0.25	100	1
SZ212V5	2.5	20	30	1200	0.25	100	1
SZ212V7	2.7	20	30	1300	0.25	75	1
SZ213V0	3	20	30	1600	0.25	50	1
SZ213V3	3.3	20	28	1600	0.25	25	1
SZ213V6	3.6	20	24	1700	0.25	15	1
SZ213V9	3.9	20	23	1900	0.25	10	1
SZ214V3	4.3	20	22	2000	0.25	5	1
SZ214V7	4.7	20	19	1900	0.25	5	2
SZ215V1	5.1	20	17	1600	0.25	5	2
SZ215V6	5.6	20	11	1600	0.25	5	3
SZ216V2	6.2	20	7	1000	0.25	5	4
SZ216V8	6.8	20	5	750	0.25	3	5
SZ217V5	7.5	20	6	500	0.25	3	6
SZ218V2	8.2	20	8	500	0.25	3	6.5
SZ219V1	9.1	20	10	600	0.25	3	7
SZ2110	10	20	17	600	0.25	3	8
SZ2111	11	20	22	600	0.25	2	8.4
SZ2112	12	20	30	600	0.25	1	9.1
SZ2113	13	9.5	13	600	0.25	0.5	9.9
SZ2114	14	9	15	600	0.25	0.1	10
SZ2115	15	8.5	16	600	0.25	0.1	11
SZ2116	16	7.8	17	600	0.25	0.1	12
SZ2118	18	7	21	600	0.25	0.1	14
SZ2120	20	6.2	25	600	0.25	0.1	15
SZ2122	22	5.6	29	600	0.25	0.1	17
SZ2124	24	5.2	33	600	0.25	0.1	18
SZ2127	27	4.6	41	600	0.25	0.1	21
SZ2128	28	4.5	44	600	0.25	0.1	21
SZ2130	30	4.2	49	600	0.25	0.1	23
SZ2133	33	3.8	58	700	0.25	0.1	25
SZ2136	36	3.4	70	700	0.25	0.1	27
SZ2139	39	3.2	80	800	0.25	0.1	30
SZ2140	40	3.0	100	800	0.25	0.1	31
SZ2147	47	2.7	150	1000	0.25	0.1	36

Note: ①V_Z Tolerance is ±5%

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Mechanical Dimensions: In mil (mm)



Bottom side metalization Ag-5kA minimum
 Top side metalization AlSiCu -25kA minimum
 Bottom side is cathode, top side is anode
 Dimension H =8.2±1(0.21±0.025) (It can be customized according to customer requirements)

A	B
21 ± 2(0.53 ± 0.05)	15 ± 2(0.38 ± 0.05)

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